Thermal GP1200 ®ý?ìWm&¬

LabData Sheet A2023.06

Thermal GP1200 ®û?ìGDOõ&ªAF5. ÿ:=i×*û?ì/&OüEƒ6O4˜o "Ëfa.-K—WÄ `L ~D'4õ , Oü( "Ð?ì%g õ&'4b?ìAF1 `Ð+]-"-¦ Jdó6ƒ-ùQn(|Eƒ*û?ì_ \îo M"ŠN(!š WgB¯ ù^, MEƒ?ìe:#‹^,(|EƒD4; MÜN Ax/& <

Thermal GP1200 thermal conductive silicone gap pad is a kind of material with high thermal conductivity. Owing to double-sided natural tackiness, the material can build up a good heat conduction path between the heat sink and the metal substrate during assembly. The product shows low thermal resistance and good electrical insulation properties under low compression force.

Features Az/(

- Thermal Conductivity *û?ìKú4o 12.0 W/m·K
- Natural Tackiness PémÎ/&
- Low Compress Stress M"ŠN(-"!š
- Low Thermal Resistance M?ìe:

Property Az/(	Typical Value y&Œ =	Unit "V N	Test Method <LZÖ4º;Ö
Composition <X,1 !	Silicone Filled with Thermal Powder GDOõ&û?iKˆ R		—
Color g•Qs	Gray ?oQq	—	Visual EíXÅ

Applications ¨#Â-•D)

- Consumer Electronics <‡\8D4*O
- Network Equipment NP_ Z½(
- Voltage Regulation Modules D4"Š[Q•9 &V
- High Speed Storage Drive i×_ *W §ip!§%g

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and need to take all the risks and responsibilities to use.

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